

C0805C333K3GECTU

Aliases (C0805C333K3GEC7800)

ESD SMD Comm COG, Ceramic, 0.033 uF, 10%, 25 VDC, COG, SMD, MLCC, Temperature Stable, Electro Static Discharge, Class I, 0.7 mm, 0805 / 2012



Click [here](#) for the 3D model.

General Information

Series	ESD SMD Comm COG
Style	SMD Chip
Description	SMD, MLCC, Temperature Stable, Electro Static Discharge, Class I
Features	Temperature Stable, Low ESR, Class I
RoHS	Yes
Termination	Tin
Marking	No
Typical Component Weight	14 mg
Shelf Life	78 Weeks
MSL	1

Specifications

Capacitance	0.033 uF
Measurement Condition	1 kHz 1.0Vrms
Tolerance	10%
Voltage DC	25 VDC
ESD Level per AEC-Q200	25,000 V ESD Level
Dielectric Withstanding Voltage	62.5 VDC
Temperature Range	-55/+125°C
Temp. Coefficient	COG
Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC)	30 ppm/C, 1kHz 1.0Vrms
Dissipation Factor	0.1% 1 kHz 1.0Vrms
Aging Rate	0% Loss/Decade Hour
Insulation Resistance	30.303 GOhms

Dimensions

L	2mm +/-0.2mm
W	1.25mm +/-0.2mm
T	1.25mm +/-0.15mm
S	0.7mm MIN
B	0.5mm +/-0.25mm
Case Code (EIA / mm)	0805 / 2012

Packaging Specifications

Packaging	T&R, 180mm, Plastic Tape
Packaging Quantity	2500

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